FEE TRANSMITTAL

Electronic Version v08

Stylesheet Version v08.0

Title of Invention

METHOD FOR FORMING INTERCONNECTS ON THIN WAFERS

Application Number:

Date:

First Named Applicant: Leonard J Gardecki
Attorney Docket Number: BUR920030026US1

TOTAL FEE AUTHORIZED \$ 934

Patent fees are subject to annual revisions on or about October 1st of each year.

Filing as large entity

BASIC FILING FEE

Fee Description	Fee Code	Amount \$	Fee Paid \$			
Utility Filing Fee	1001	750	750			
Subtotal For Basic Filing Fees: \$ 750						

EXTRA CLAIM FEES

Fee Description	Extra Claim	Fee Code	Amount \$	Fee Paid \$
Total Claims : 28	8	1202	18	144
Independent Claims : 3	0	1201	84	0
			Subtotal For Extra	Claims Fees: \$ 144

ASSIGNMENT FEES

Fee Description	Property Number	Quantity	Fee Code	Amount \$	Fee Paid \$	
Recording Each Patent	00000000	1	8021	40	40	
Assignment Per Property Fee						
Subtotal For Additional Fees: \$40						

AUTHORIZED BILLING INFORMATION

The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:

Deposit account number: 090456

Access Code ****

Deposit name: International Business Machines Corporation

Deposit authorized name: William D. Sabo

Signature: William D. Sabo/s/

Date (YYYYMMDD): 2003-06-13

Charge Assignment Fees Required Under 37 C.F.R. Section 1.21 (h).

Charge Any Additional Fee Required Under 37 C.F.R. Sections 1.16 and 1.17.